

PCN Number:	20221121000.1		PCN Date:	November 21, 2022	
Title:	Qualification of CDAT as an alternate Assembly site for select devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Feb 19, 2023	Sample Requests accepted until:	Dec 21, 2022*		
*Sample requests received after Dec 21, 2022 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for set of devices listed below. Construction differences are as follows:					
	ASEN	UTL1	CDAT		
Mold Compound	SID#1800900161	SID#CZ0138	4222198		
Mount Compound	SID#1400336111	SID#PZ0076	4226215 or 4226215 + 4221460		
MSL	2	2	1		
Bond wire composition, diameter	Au, 0.8 mil	Au, 0.8 mil	Cu, 0.8 or 0.7 mil		
Reason for Change:					
Supply continuity					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
ASEN	ASN	CHN	Suzhou		
UTL1	NSE	THA	Bangkok		
CDAT	CDA	CHN	Chengdu		

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TUSB211HIRW BR	TUSB212RW BR	TUSB214RW BT	TUSB320LIRW BR
TUSB211IRW BR	TUSB212RW BT	TUSB320HAIRW BR	TUSB320RW BR
TUSB211RW BR	TUSB214IRW BR	TUSB320HIRW BR	TUSB321AIRW BR
TUSB212IRW BR	TUSB214IRW BT	TUSB320IRW BR	TUSB321RW BR
TUSB212IRW BT	TUSB214RW BR	TUSB320LAIRW BR	TUSB322IRW BR



TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TUSB320LAIRWBR	QBS Process Reference: TWL3033H3IZXX	QBS Package Reference: TMP451AIDQFR	QBS Package Reference: TLV9024RTER	QBS Package Reference: TLV9034RTER
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/4608/0	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	1/77/0	2/154/0
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-	1/77/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0	1/77/0	2/154/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0	2/154/0
WBP	Bond Pull	Wires	1/30/0	-	-	-	-
WBP	Wire Pull	Wires	1/30/0	-	-	-	-
WBS	Ball Bond Shear	Wires	1/30/0	-	-	-	-

- QBS: Qual By Similarity
- Qual Device is qualified at LEVEL1-260C: TUSB320LAIRWBR
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2211-006

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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